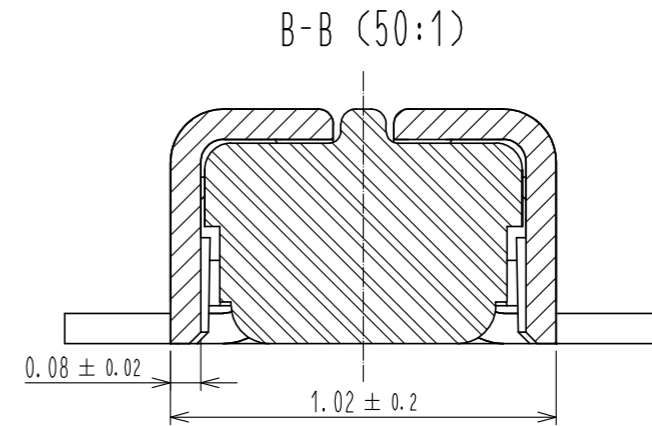
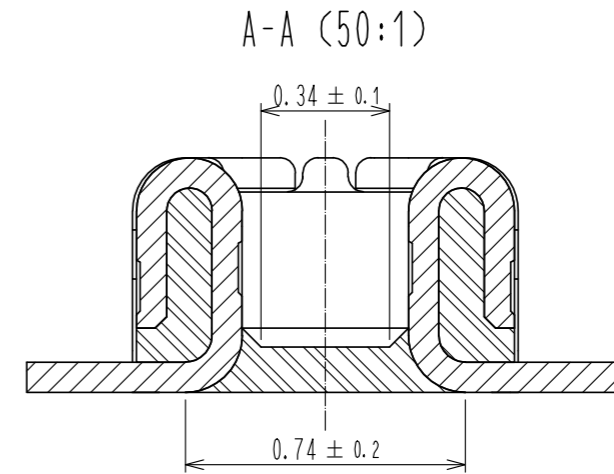
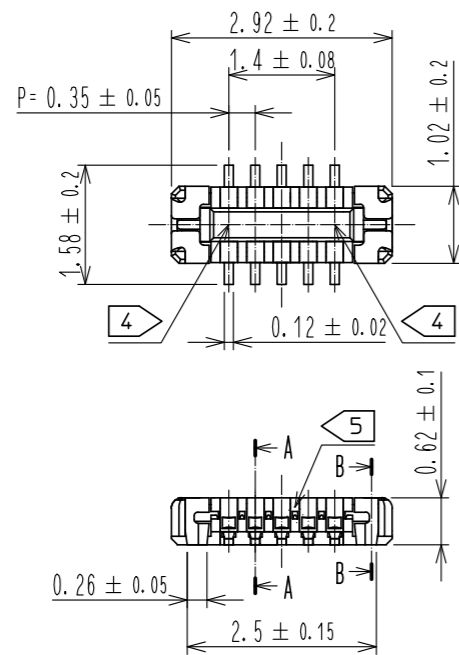
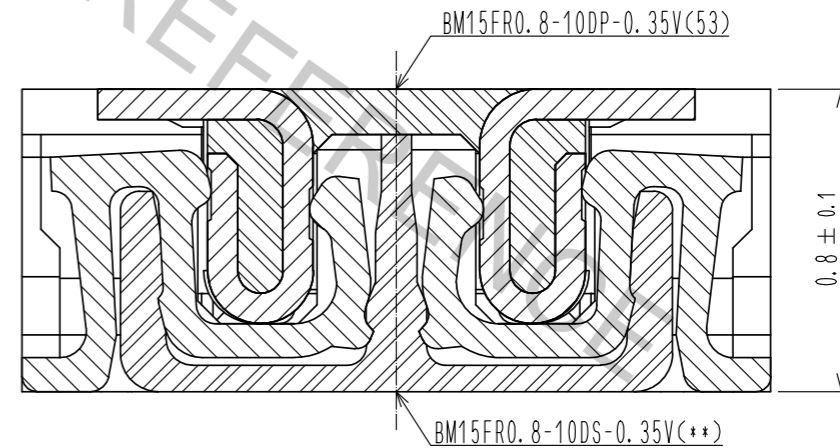


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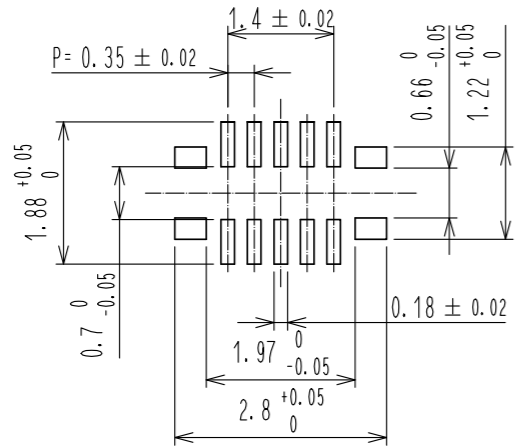
ENGAGEMENT FIGURE (50:1)



- NOTE) 1 . ALL LEAD CO-PLANARITY SHALL BE 0.08mm MAX
- 2 CONTACT PLATING SPECIFICATIONS
 CONTACT AREA : GOLD 0.05 μm MIN
 SMT LEAD : GOLD 0.05 μm MIN
 UNDERPLATING : NICKEL 1 μm MIN
 (SURFACE : SEALING)
- 3 REINFORCED METAL FITTINGS LOCK
 SMT LEAD : GOLD 0.05 μm MIN
 UNDERPLATING : NICKEL 1 μm MIN
 (SURFACE : SEALING)
- 4 CAV No. AND HRS MARK MYE BE INDICATED IN APPROX POSITION SHOWN.
- 5 A PART OF THE WALL COULD BE NOTCHED.

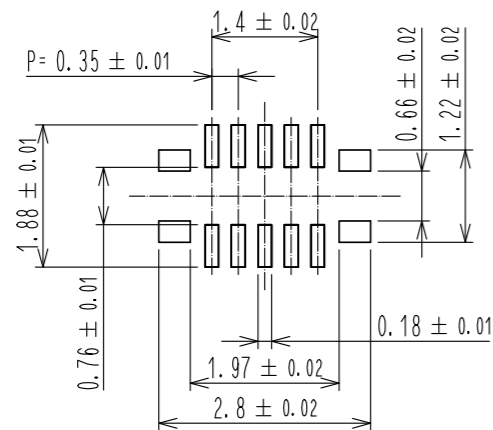
4	PS	CLEAR (ENBOSSED CARRIER TAPE)						
3	PHOSPHOR BRONZE	3	7	PS	CLEAR (REINFORCEMENT COLLAR)			
2	PHOSPHOR BRONZE	2	6	PS	BLACK (PLASTIC REEL)			
1	LCP	UL94 V-0, BLACK	5	POLYESTER	CLEAR (COVER TAPE)			
NO.	MATERIAL	FINISH . REMARKS	NO.	MATERIAL	FINISH . REMARKS			
UNITS mm		SCALE 10 : 1	COUNT 	DESCRIPTION OF REVISIONS		DESIGNED	CHECKED	DATE
HRS HIROSE ELECTRIC CO., LTD.		APPROVED : MO. ISHIDA	16.01.08	DRAWING NO. EDC-355886-53-01				
		CHECKED : TS. MIYAZAKI	16.01.08	PART NO. BM15FRO.8-10DP-0.35V(53)				
		DESIGNED : SH. HOSODA	16.01.07	CODE NO. CL673-1226-8-53				
		DRAWN : KR. AJITO	16.01.07					

◆ RECOMMENDED PCB LAYOUT

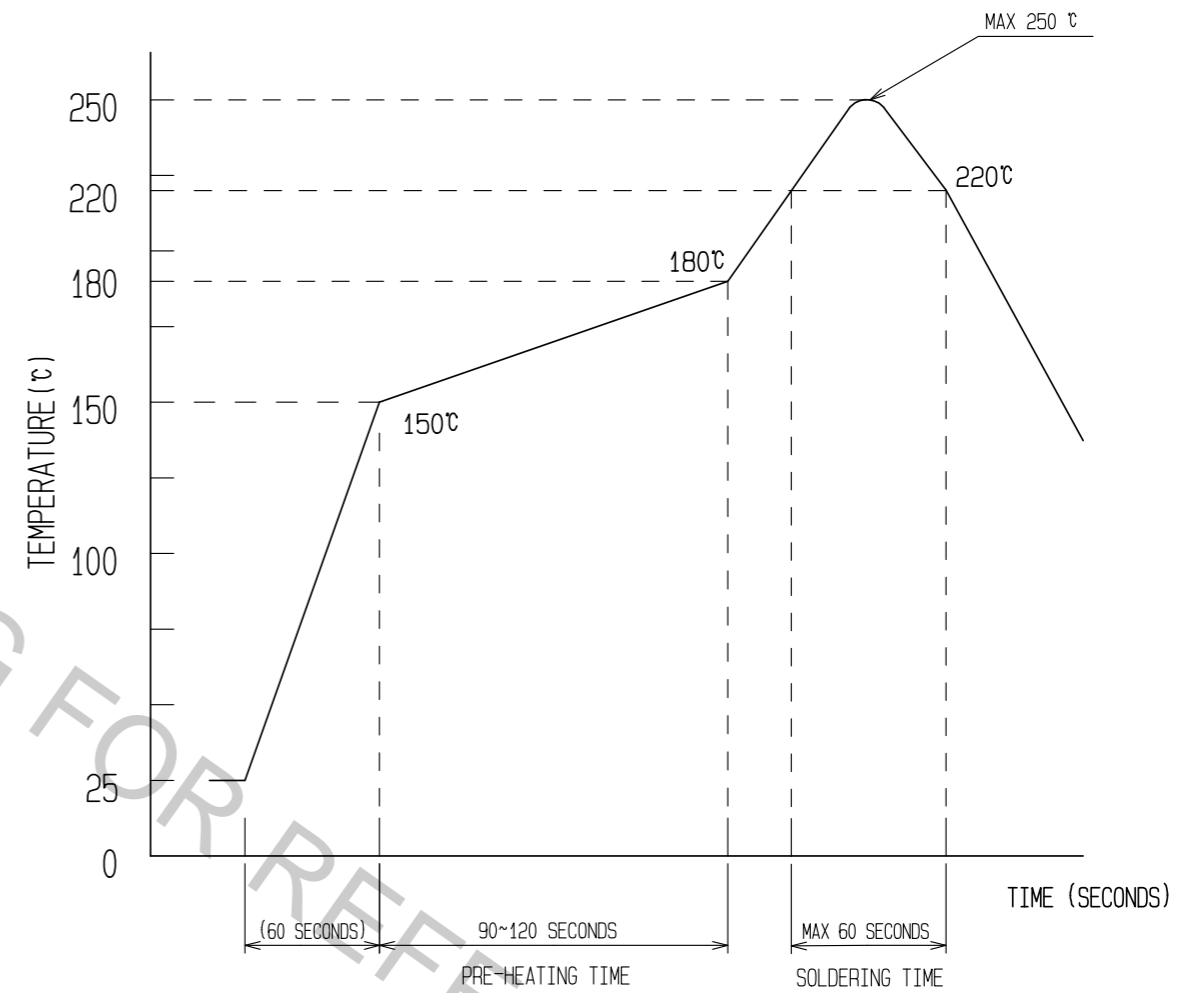


◆ RECOMMENDED METAL MASK DIMENSIONS

METAL MASK THICKNESS : 100 μm



⑥ RECOMMENDED REFLOW TEMPERATURE PROFILE USING LEAD-FREE SOLDER PASTE.

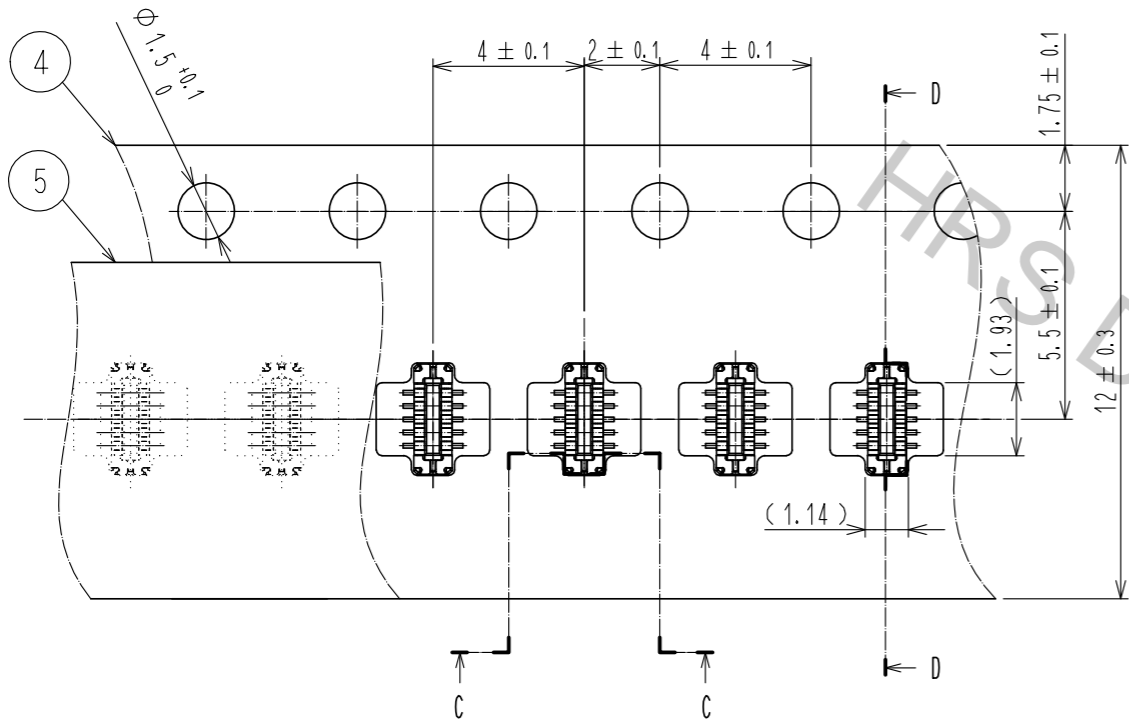


- REFLOW METHOD: IR REFLOW
 NUMBER OF REFLOW CYCLES: 2 CYCLES MAX.
- REFLOW TIME
 DURATION ABOVE 220°C, 60 SEC. MAX.
 (PEAK TEMPERATURE: 250°C MAX)
 - PRE-HEAT TIME
 PRE-HEAT TEMPERATURE(MIN): 150°C
 PRE-HEAT TEMPERATURE(MAX): 180°C
 PRE-HEAT TIME: 90-120 sec.

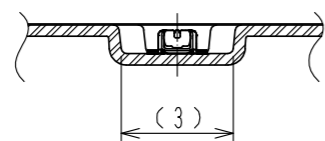
⑥ THIS TEMPERATURE PROFILE IS PER THE CONDITIONS SHOWN ABOVE. ADDITIONAL FACTORS, SUCH AS SOLDER PASTE TYPE, PCB SIZE AND OTHER MOUNTED COMPONENTS COULD AFFECT THE PROFILE, THEREFORE, A THOROUGH EVALUATION OF MOUNTING CONDITION IS REQUIRED PRIOR TO PRODUCTION. TEMPERATURE IS MEASURED AT CONTACT LEAD.

HRS	DRAWING NO.	EDC-355886-53-01
	PART NO.	BM15FR0.8-10DP-0.35V<53>
	CODE NO.	CL673-1226-8-53

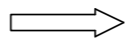
EMBOSSED CARRIER TAPE PACKAGING (5:1)



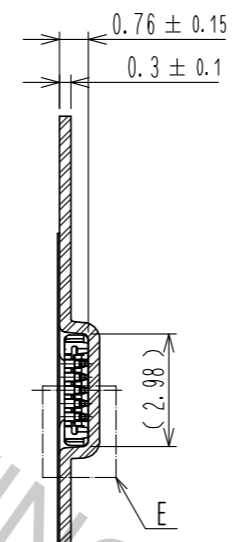
C-C (5:1)



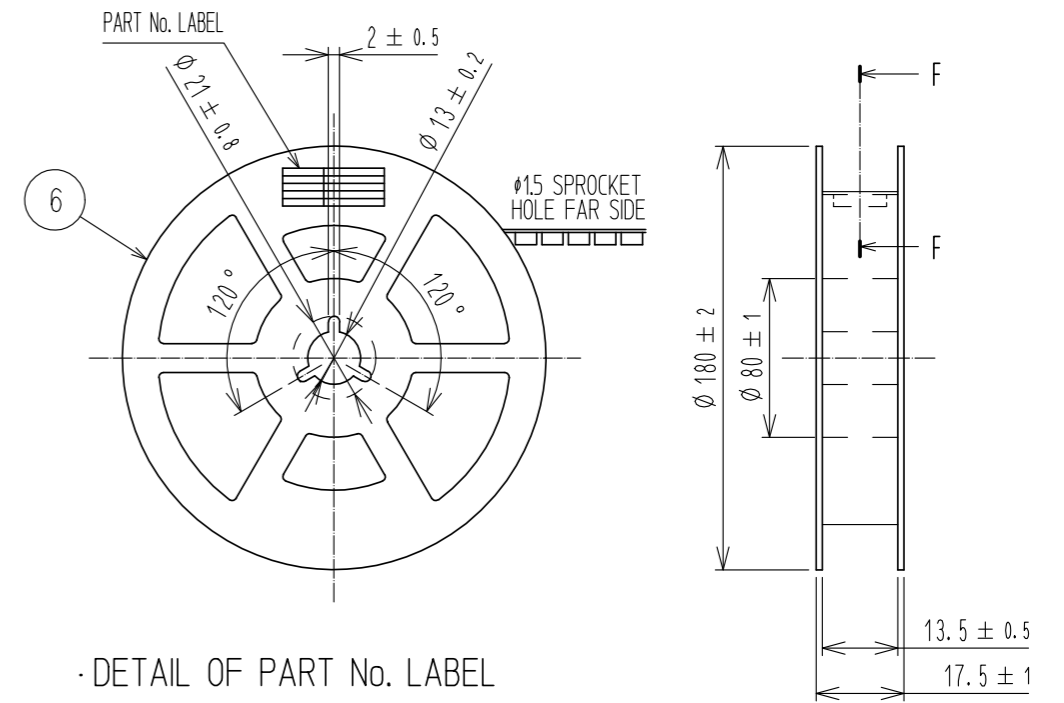
DIRECTION OF UNREELING



D-D (5:1)



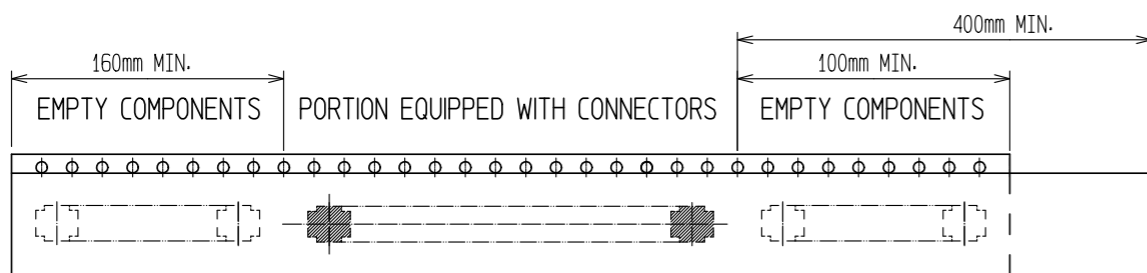
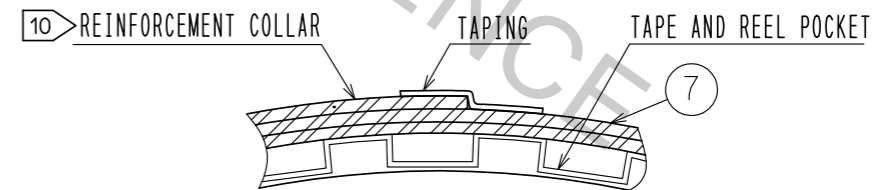
STYLE AND DIMENTION OF REEL (FREE)



DETAIL OF PART No. LABEL

SUPPLIER	
QUANTITY	
PART No.	
CODE No.	
DATE OF MANUFACTURED	
製造年月日	** ** *
製品コード	CL673-1226-8-53
製品名	BM15FR0.8-10DP-0.35V(53)
数量	1,000
納入者	ヒロセ電機(株)

F-F (FREE)

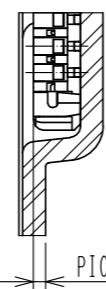


TRAILER

TAPING (FREE)

LEADER

E(10:1)



- 7. PER REEL 1000 CONNECTORS.
- 8. THE DIMENSIONS IN PARENTHESSES ARE FOR REFERENCE.
- 9 REFER TO JIS C 0806 AND IEC 60286-3
(PACKAGING OF COMPONENTS FOR AUTOMATIC HANDLING)
- 10 AFTER PACKAGING, ROLL 2 METERS OF THE REINFORCEMENT COLLAR TO OUTER CIRCUMFERENCE OF TAPE AND REEL POCKET, AND TAPE DOWN AT THE END THE COLLAR.

HRS

DRAWING NO.	EDC-355886-53-01
PART NO.	BM15FR0.8-10DP-0.35V(53)
CODE NO.	CL673-1226-8-53

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